(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
26 November 2009 (26.11.2009)

PCT

(10) International Publication Number
WO 2009/142692 A3

(51) **International Patent Classification**:
C09K 3/14 (2006.01)

(21) **International Application Number**:
PCT/US2009/002846

(22) **International Filing Date**:
7 May 2009 (07.05.2009)

(25) **Filing Language**: English

(26) **Publication Language**: English

(30) **Priority Data**:
12/126,739 23 May 2008 (23.05.2008) US

(71) **Applicant** *(for all designated States except US)*: **CABOT MICROELECTRONICS CORPORATION** [US/US]; Legal Department, 870 North Commons Drive, Aurora, IL 60504 (US).

(72) **Inventors**: **WHITE, Michael**; c/o Legal Department, Cabot Microelectronics Corporation, 870 North Commons Drive, Aurora, IL 60504 (US). **GILLILAND, Jeffrey**; c/o Legal Department, Cabot Microelectronics Corporation, 870 North Commons Drive, Aurora, Illinois 60504 (US). **JONES, Lamon**; c/o Legal Department, Cabot Microelectronics Corporation, 870 North Commons Drive, Aurora, Illinois 60504 (US). **WALTERS, Alicia**; c/o Legal Department, Cabot Microelectronics Corporation, 870 North Commons Drive, Aurora, Illinois 60504 (US).

(74) **Agents**: **WESEMAN, Steven** et al.; Associate General Counsel, Intellectual Property, Cabot Microelectronics Corporation, 870 North Commons Drive, Aurora, IL 60504 (US).

(81) **Designated States** *(unless otherwise indicated, for every kind of national protection available)*: AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RS, RU, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, UZ, VC, VN, ZA, ZM, ZW.

(84) **Designated States** *(unless otherwise indicated, for every kind of regional protection available)*: ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Declarations under Rule 4.17:

— *as to applicant's entitlement to apply for and be granted a patent (Rule 4.17(ii))*

— *as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii))*

Published:

— *with international search report (Art. 21(3))*

— *before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments (Rule 48.2(h))*

(88) **Date of publication of the international search report**:
18 February 2010

WO 2009/142692 A3

(54) **Title**: STABLE, HIGH RATE SILICON SLURRY

(57) **Abstract**: The invention provides a chemical mechanical polishing composition comprising wet process silica, a stabilizer compound, a potassium salt, a secondary amine compound, and water. The invention further provides a method of polishing a substrate with the polishing composition.